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(12) United States Design Patent

Li

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(54) **CIRCUIT BOARD**

(71) Applicant: **Xiuling Li**, Guangdong (CN)

(72) Inventor: **Xiuling Li**, Guangdong (CN)

(**) Term: **15 Years**

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(52) **U.S. Cl.**
USPC **D13/182**

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See application file for complete search history.

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Primary Examiner — Sandra Snapp
Assistant Examiner — Anehita E. Oribabor
(74) *Attorney, Agent, or Firm* — Edward Darius Robinson

(57) **CLAIM**

The ornamental design for a circuit board as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a circuit board showing my new design;
FIG. **2** is another perspective view thereof;
FIG. **3** is a front elevational view thereof;
FIG. **4** is a rear elevational view thereof;
FIG. **5** is a left side elevational view thereof;
FIG. **6** is a right side elevational view thereof;
FIG. **7** is a top plan view thereof; and,
FIG. **8** is a bottom plan view thereof.
The broken lines in the drawings depict portions of the circuit board that form no part of the claimed design.

1 Claim, 8 Drawing Sheets